

/ Descriptions

WR0553 ММ Ё QSQ æ Ñ ç s ll 1 Silicon NPN transistor in a TO-220 Plastic Package.

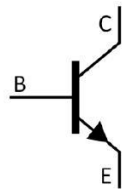
/ Features

F0E ð я æ ε Y_{FER}@483Y ζ ι ρ ð ll ð ll º ε l_F@8D ζ
High Collector-Base Voltage, High Collector Current.

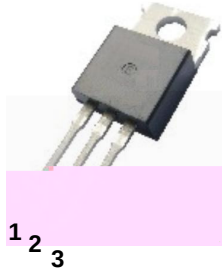
/ Applications

тнъ с ð ð ϕ ð ç ρ,
B/W TV horizontal deflection output.

/ Equivalent Circuit



/ Pinning



PIN1 χ Base PIN 2 χ Collector PIN 3 χ Emitter

/ h_{FE} Classifications & Marking

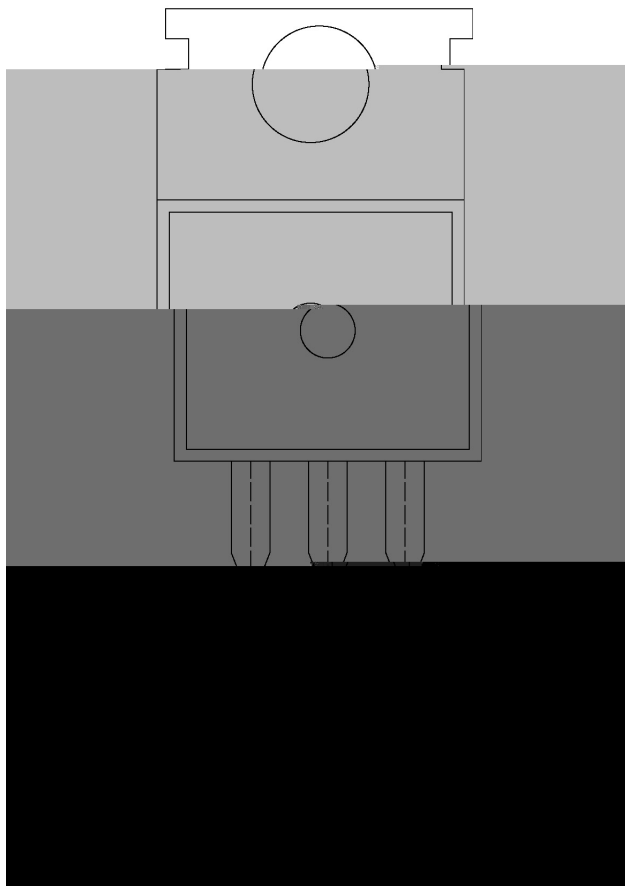
h _{FE} Classifications Symbol	N	R	O
h _{FE} Range	20 50	40 80	70 140

/ Electrical Characteristic Curve

The technical drawing illustrates a mechanical component through two primary views: a top view (plan) and a side view (elevation).

- Top View:** This view shows the horizontal footprint of the part. It features a central rectangular section with a width dimensioned as a . To the left of this section is another feature with a width dimensioned as b_1 . The total width of the part is indicated by dimension C . On the right side, there is a semi-circular feature with a radius dimensioned as c . The distance from the center of the semi-circle to the right edge is labeled a_1 .
- Side View:** This view shows the profile of the part. It highlights a vertical face with a height dimensioned as B . The top surface of this face is inclined at an angle of 3° relative to the horizontal.
- Dimensions and Angles:**
 - A : Horizontal distance between the left edge of the main body and the start of the semi-circular feature.
 - B : Vertical height of the main body.
 - C : Total horizontal width of the part.
 - a : Width of the central rectangular section.
 - b_1 : Width of the leftmost rectangular section.
 - c : Radius of the semi-circular feature.
 - a_1 : Distance from the center of the semi-circle to its right edge.
 - 3° : Angle of inclination of the top surface.

/ Marking Instructions



() / Temperature Profile for Dip Soldering(Pb-Free)



б " X

1. 25~150 °C, Time: 60~90sec;
2. 255±5 °C, Duration: 5±0.5sec;
3. Cooling Speed: 2~10 °C/sec.

Note:

- 1.Preheating:25~150 °C, Time:60~90sec.
- 2.Peak Temp.:255±5 °C, Duration:5±0.5sec.
3. Cooling Speed: 2~10 °C/sec.

/ Resistance to Soldering Heat Test Conditions

270±5 °C, Time: 10±1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

“Q” Y E

BULK

Package Type 封装形式	Units 包					Dimension 包尺寸 (unit: mm ³)		
	Units/Bag 只/袋	Bags/Inner Box 袋/套	Units/Inner Box 只/套	Inner Boxes/Outer Box 套/箱	Units/Outer Box 只/箱	Bag 袋	Inner Box 套	Outer Box 箱
TO-220/F	200	10	2,000	5	10,000	135×190	237×172×102	560×245×195

“1” Y E

TUBE

Package Type 封装形式	Units 包					Dimension 包尺寸 (unit: mm ³)		
	Units/Tube 只/套	Tubes/Inner Box 套/套	Units/Inner Box 只/套	Inner Boxes/Outer Box 套/箱	Units/Outer Box 只/箱	Tube 套	Inner Box 套	Outer Box 箱
TO-220/F								